

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of	)	Attorney Docket No.: <b>MIYOSH0008</b>
	)	
Seiichi AKAGI et al.	)	Confirmation No.: 6701
	)	
Serial No.: 10/598,515	)	Group Art Unit: 1796
	)	
Filed: September 1, 2006	)	Examiner: Hannah J. PAK
	)	
For: SEALANT EPOXY-RESIN MOLDING	)	Date: February 22, 2010
MATERIAL, AND ELECTRONIC	)	
COMPONENT DEVICE	)	

**AMENDMENT (D)**

**MAIL STOP: AMENDMENT**  
U.S. Patent and Trademark Office  
Customer Service Window  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

Sir:

In response to the non-final Office Action mailed August 21, 2009, please enter the following remarks in the application identified above:

**Amendments to the Claims** are reflected by the Listing of Claims that begins on page 2 of this paper.

**Remarks/Arguments** begin on page 11 of this paper.